

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A semiconductor device comprising:

a substrate;

a semiconductor chip arranged on the substrate;

a first electrode formed in the substrate and connected to the semiconductor chip;

a concave portion provided on a side of the substrate, the concave portion extending from a back of the substrate and ~~terminating in~~ not reaching a top of the substrate, and at least part of the first electrode being exposed to the concave portion; and

a metal layer formed on ~~the~~ said at least part of the first electrode.

Claim 2 (Currently Amended): The semiconductor device according to claim 1, wherein the metal layer ~~is short of~~ does not reach the side of the substrate.

Claim 3 (Original): The semiconductor device according to claim 1, wherein the substrate is a multilayer substrate including at least two layers.

Claim 4 (Original) The semiconductor device according to claim 3, wherein the concave portion is provided in a layer other than an uppermost layer of the multilayer substrate.

Claim 5 (Original): The semiconductor device according to claim 3, wherein the concave portion is provided in a layer other than a multilayer including an uppermost layer of the multilayer substrate.

Claim 6 (Original): The semiconductor device according to claim 3, wherein the concave portion is provided in a lowermost layer of the multilayer substrate.

Claim 7 (Original): The semiconductor device according to claim 3, wherein the concave portion is provided in a multilayer including a lowermost layer of the multilayer substrate and excluding an uppermost layer of the multilayer substrate.

Claim 8 (Original): The semiconductor device according to claim 1, wherein the semiconductor chip comprises an active element.

Claim 9 (Original): The semiconductor device according to claim 1, wherein the semiconductor chip comprises an active element and a passive element.

Claim 10 (Original): The semiconductor device according to claim 1, further comprising sealing resin formed on the substrate, the semiconductor chip, and the first electrode.

Claim 11 (Original): The semiconductor device according to claim 10, wherein the sealing resin includes a magnetic substance.

Claim 12 (Original): The semiconductor device according to claim 1, further comprising a second electrode formed in the substrate separately from the first electrode, and the semiconductor chip being arranged on a top of the second electrode.

Claim 13 (Original): The semiconductor device according to claim 1, wherein the semiconductor chip and the first electrode are connected to each other through a bonding wire.

Claim 14 (Original): The semiconductor device according to claim 1 wherein the concave portion is one of a quadrilateral and a semicircle.

Claim 15 (Original): The semiconductor device according to claim 1, which comprises a leadless package structure.